Nomenclature for DRAM Component

Ver.3.1

1 2	3	4 5	6	7 8	9 10	11	12	13	14	15 16	17
HX	**B**	**15**	**H**	**1G**	**40**	**0**	**A**	**F**	**-**	**13**	**K**

Identifier
HX = UniIC Identifi

Product Group
B = Commodity chip
I = Industrial Temperature chip

DRAM Volatge
13 = 1.35V
15 = 1.5V
18 = 1.8V
25 = 2.5V
33 = 3.3V

DRAM Generation
S = SDRAM
D = DDR
T = DDR2
H = DDR3

DRAM Density
1G = 1 Gbit
2G = 2 Gbit
4G = 4 Gbit
8G = 8 Gbit
16 = 16 Mbit
32 = 32 Mbit
64 = 64 Mbit
128 = 128 Mbit
256 = 256 Mbit
512 = 512 Mbit

Number of IOs of Device
40 = x4
80 = x8
16 = x16
32 = x32

Die Numbers
0 = Monolytic
2 = 2 dies
4 = 4 dies

Latencies
A = 2-2-2
B = 3-3-3
C = 4-4-4
D = 5-5-5
E = 6-6-6
F = 7-7-7
G = 8-8-8
H = 9-9-9
J = 10-10-10
K = 11-11-11
L = 12-12-12
M = 13-13-13

Speed Bin
3 = 333 MHz
4 = 250 MHz
5 = 200 MHz
6 = **166** MHz
7 = 143 MHz
11 = 933 MHz
13 = 800 MHz
15 = 667 MHz
19 = 533 MHz
25 = 400 MHz
37 = 267 MHz
75 = 133 MHz

Power
- = Standard
L = Low power

Package
C = FBGA black
T = TSOPII black
E = TSOPII green
F = FBGA green
G = TSOP stack green

Die Revision
A = Frist product
B = Second product
C = Third product